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- as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for the following designations AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)
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(54) Title: COATING COMPOSITIONS COMPRISING EPOXY RESINS AND AMINOFUNCTIONAL SILICONE RESINS

(57) Abstract: This invention relates to a coating composition comprising (A) 100 weight parts of at least one epoxy resin; (B) 3-300 weight parts of at least one aminofunctional silicone resin; (C) up to 50 weight parts of at least one organic hardener; (D) up to 100 weight parts of at least one epoxyfunctional silicone resin; and (E) up to 10 weight parts of at least one cure accelerator. The coating compositions of this invention have acceptable moduli (>100MPa), are tough, flexible, solvent and water resistant over a broad temperature range.

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